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| APPLICATION NO. | FILING DATE | FIRST NAMED INVENTOR | ATTORNEY DOCKET NO. | CONFIRMATION NO. |
|---|-----------------|----------------------|-------------------------|------------------|
| 09/987,010 | 11/13/2001 | Tetsuyoshi Inoue | 204552021700 | 6384 |
| | 7590 06/17/2004 | | EXAMINER | |
| | BRETSCHNEIDER | | NGUYEN, TUAN N | |
| MORRISON & FOERSTER LLP 1650 TYSONS BLVD., SUITE 300 | | | ART UNIT | PAPER NUMBER |
| MCLEAN, V | * | | 2828 | |
| | | | DATE MAILED: 06/17/200- | 4 |

Please find below and/or attached an Office communication concerning this application or proceeding.

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|---|---|--|---|--|--|--|
| | Applicati n N . | Applicant(s) | | | | |
| | 09/987,010 | INOUE ET AL. | | | | |
| Office Action Summary | Examiner | Art Unit | | | | |
| | Tuan N Nguyen | 2828 | | | | |
| Th MAILING DATE of this communication Period f r Reply | n appears on the cover she tw | th the correspondence address | | | | |
| A SHORTENED STATUTORY PERIOD FOR F THE MAILING DATE OF THIS COMMUNICAT - Extensions of time may be available under the provisions of 37 C after SIX (6) MONTHS from the mailing date of this communicati - If the period for reply specified above, the maximum statutory - Failure to reply within the set or extended period for reply will, by Any reply received by the Office later than three months after the earned patent term adjustment. See 37 CFR 1.704(b). | ON. FR 1.136(a). In no event, however, may a con. The areply within the statutory minimum of thir period will apply and will expire SIX (6) MON statute, cause the application to become Al | reply be timely filed ty (30) days will be considered timely. ITHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133). | | | | |
| Status | | | | | | |
| 1) Responsive to communication(s) filed on | 02 April 2004. | | | | | |
| <u> </u> | This action is non-final. | | | | | |
| 3) Since this application is in condition for all | Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213. | | | | | |
| Disposition of Claims | | | | | | |
| 4) ⊠ Claim(s) 1-5 is/are pending in the applica 4a) Of the above claim(s) is/are wit 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) 1.2 and 5 is/are rejected. 7) ⊠ Claim(s) 3 and 4 is/are objected to. 8) □ Claim(s) are subject to restriction a | hdrawn from consideration. | | | | | |
| Application Papers | | | | | | |
| 9)☐ The specification is objected to by the Exa | aminer. | | | | | |
| 10) ☐ The drawing(s) filed on is/are: a) ☐ accepted or b) ☐ objected to by the Examiner. | | | | | | |
| Applicant may not request that any objection t | to the drawing(s) be held in abeyar | nce. See 37 CFR 1.85(a). | | | | |
| Replacement drawing sheet(s) including the c | • | | | | | |
| 11)☐ The oath or declaration is objected to by t | he Examiner. Note the attached | d Office Action or form PTO-152. | | | | |
| Priority under 35 U.S.C. § 119 | | | | | | |
| 12) Acknowledgment is made of a claim for for a) All b) Some * c) None of: 1. Certified copies of the priority docu 2. Certified copies of the priority docu 3. Copies of the certified copies of the application from the International B * See the attached detailed Office action for | ments have been received. ments have been received in A e priority documents have been ureau (PCT Rule 17.2(a)). | pplication No received in this National Stage | | | | |
| | | | | | | |
| Attachment(s) | 🗖 . | | | | | |
| Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PTO-94) | | Summary (PTO-413) s)/Mail Date | | | | |
| 3) Information Disclosure Statement(s) (PTO-1449 or PTO/S Paper No(s)/Mail Date | | nformal Patent Application (PTO-152) | | | | |

DETAIL ACTION

Claim Rejections - 35 USC § 102

- 1. The following is a quotation of 35 U.S.C. 102(e) which forms the basis for all obviousness rejections set forth in this Office action:
 - (e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.
- 2. Claims 1, 5 are rejected under 35 U.S.C. 102(e) as being unpatentable over Kotato et al. (US 6099678).

Kotato et al. '678 shows in figures 1, 5, 7, 9-11 and discloses a manufacturing method for a semiconductor laser device in which semiconductor chip is mounted on a base portion by using an electrically conductive die-bond paste including metal filler such as silver (Col 1: 37, 65) (Col 2: 42), by applying die-bond paste onto the base, mounting the semiconductor onto the base portion, temporary curing the die-bond paste while the semiconductor chip is kept pressurized toward the base portion (Col 2: 60-67) (Col 3: 1-12), and finally curing the conductive die-bond paste (Col 4: 6-19) (Col 6: 27-67) (Col 7: 1-10).

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

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The factual inquiries set forth in *Graham* v. *John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:

- 1. Determining the scope and contents of the prior art.
- 2. Ascertaining the differences between the prior art and the claims at issue.
- 3. Resolving the level of ordinary skill in the pertinent art.
- 4. Considering objective evidence present in the application indicating obviousness or non-obviousness.

4. Claim 2, 6 is rejected under 35 U.S.C. 103(a) as being unpatentable over Kotato et al. (US 6099678) in view of Inaba (US 6255742).

With respect to claims 2, 6 Kotato '678 discloses the above and further discloses the temperature use in curing of the bond and semiconductor (Tables 1, 5, 6), the claims 2 and 6 further discloses the thermal resistance of semiconductor laser device is 90 °C/W or lower and the content ration of silver in die-bond paste is 82%-84%. Inaba '742 shows in (Fig 9a-d: 1,2,19; Fig 11b:20, 7) a semiconductor laser device having semiconductor laser chip mounted on a based portion using electrically conductive die-bond paste (Col 8: 62-67), where thermal resistance of semiconductor device is about 30 °C/W (Col 7: TABLE 1). Also, Inaba '742 discloses the amount of die-bond surface of semiconductor laser chip (Col 8: 62-67; Col 0-60). It has been held that where the general conditions of a claim are disclosed in the prior art, discovering the optimum or workable ranges involves only routine skill in the art. *In re Aller, 105 USPQ 233*.

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Allowable Subject Matter

Claims 3, 4 are objected to as being dependent upon a rejected base claim, but would be

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allowable if rewritten in independent form including all of the limitations of the base claim and

any intervening claims, since the prior art of record and considered pertinent to the applicant's

disclosure does not teach or suggest the claimed wherein creep-up height of the conductive die-

bond paste at a side face of the semiconductor laser chip from a die-bond surface of the

semiconductor laser chip is not more then 40um; or wherein the conductive die-bond paste

interposed between a die-bond surface of the semiconductor laser chip and the base portion is

5um or lower.

Communication Information

Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Tuan N Nguyen whose telephone number is (571) 272-1948. The

examiner can normally be reached on Mon-Fri.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Don Wong can be reached on (571) 272-1834. The fax phone numbers for the

organization where this application or proceeding is assigned are (703) 872-9306 for regular

communications and (703) 872-9306 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding

should be directed to the receptionist whose telephone number is (703) 306-3329.

Tuan N. Nguyen

Supervisory Patent Examiner

Technology Center 2800